

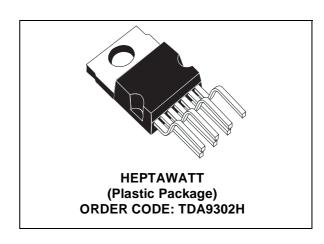
TV VERTICAL DEFLECTION OUTPUT CIRCUIT

FEATURES

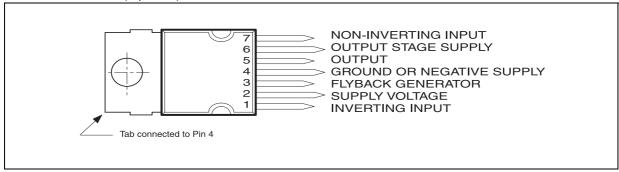
- Power Amplifier
- Flyback Generator
- Thermal Protection

DESCRIPTION

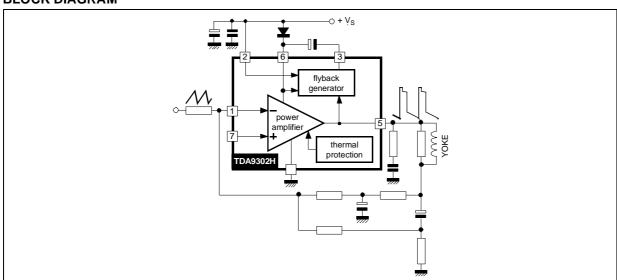
The TDA9302H is a monolithic integrated circuit in HeptawattTM package. It is a high efficiency power booster for direct driving of vertical windings of TV yokes. It is intended for use in color and black & white television as well as in monitors and displays.



PIN CONNECTION (top view)



BLOCK DIAGRAM



October 2003 1/7

TDA9302H

1 ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _S	Supply Voltage (pin 2)	35	V
V ₅ , V ₆	Flyback Peak Voltage	60	V
V ₃	Voltage at Pin 3 (see Note 1)	V _S + 3	V
V ₁ , V ₇	Amplifier Input Voltage	V _S - 0.5	V
I ₀	Output Peak Current (non repetitive, t = 2ms)	1.8	Α
I ₀	Output Peak Current at f = 50 to 200 Hz, t ≤ 10µs	±4	Α
I ₀	Output Peak Current at f = 50 to 200 Hz, t > 10µs	1.5	Α
l ₃	Pin 3 DC Current at V ₅ < V ₂	100	mA
l ₃	Pin 3 Flyback Current at f = 50 to 200 Hz, t _{fly} ≤ 1.5ms	±1.5	Α
l ₃	Pin 3 Sink Current at f = 50 to 200 Hz, t ≤ 10µs	4	Α
P _{tot}	Total Power Dissipation at T _{case} = 90 °C	20	W
T _{stg} , T _j	Storage and Junction Temperature	-40, +150	°C

Note 1: This occurs during the first part of flyback pulse

2 THERMAL DATA

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Thermal Resistance Junction-case	3	°C/W

3 ELECTRICAL CHARACTERISTICS

(refer to the test circuits, $V_S = 35V$, $T_{amb} = 25$ °C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
l ₂	Pin 2 Quiescent Current	$I_3 = 0, I_5 = 0$		8	16	mA	1
I ₆	Pin 6 Quiescent Current	$I_3 = 0, I_5 = 0$		16	36	mA	1
I ₁	Amplifier Input Bias Current	$V_1 = 1 \text{ V}, V_7 = 2 \text{ V}$		- 0.1	- 1	μΑ	1
		$V_1 = 2 \text{ V}, V_7 = 1 \text{ V}$		- 0.1	- 1	μΑ	1
V_{3L}	Pin 3 Saturation Voltage to GND	I ₃ = 20 mA		1	1.5	V	3
V_5	Quiescent Output Voltage	$V_S = 35V, R_a = 39 \text{ k}\Omega$		18		V	4
V _{5L}	Output Saturation Voltage to GND	I ₅ = 1 A		0.9	1.3	V	3
		$I_5 = 0.7 \text{ A}$		0.7	1	V	3
V _{5H}	Output Saturation Voltage to Supply	- I ₅ = 1 A		1.5	2	V	2
		- I ₅ = 0.7 A		1.3	1.8	V	2
Tj	Junction Temperature for Thermal Shutdown			140		°C	

Figure 1. Measurement of I_1 , I_2 , I_6

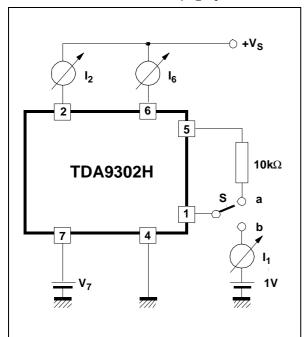
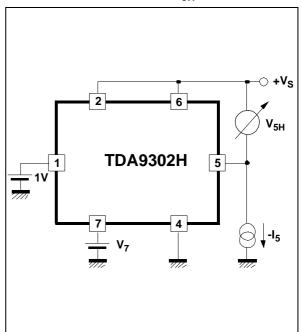


Figure 2. Measurement of V_{5H}



S1: (a) I2 and I6; (b) I1

Figure 3. Measurement of $\mathrm{V_{3L}},\,\mathrm{V_{5L}}$

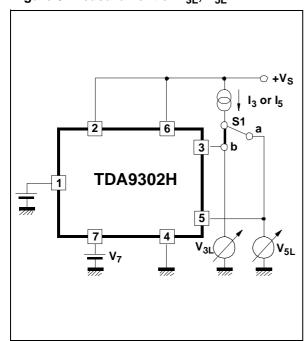
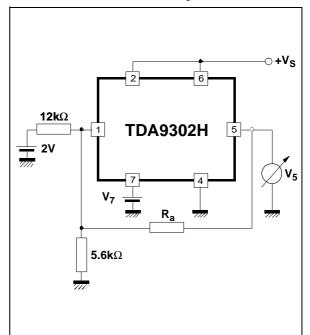
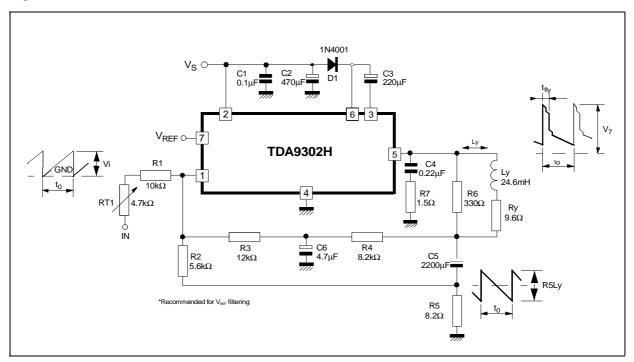


Figure 4. Measurement of V_5



S: (a) V3L; (b) V5L

Figure 5. AC test circuit

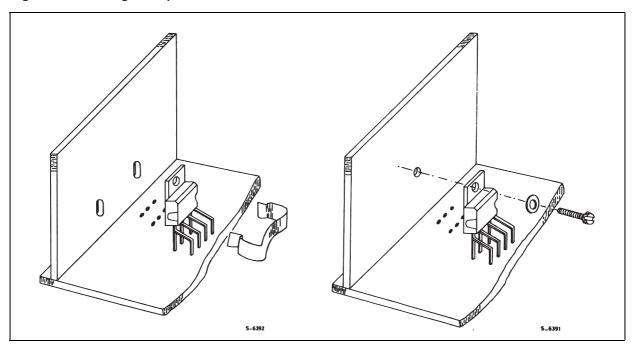


4 MOUNTING INSTRUCTIONS

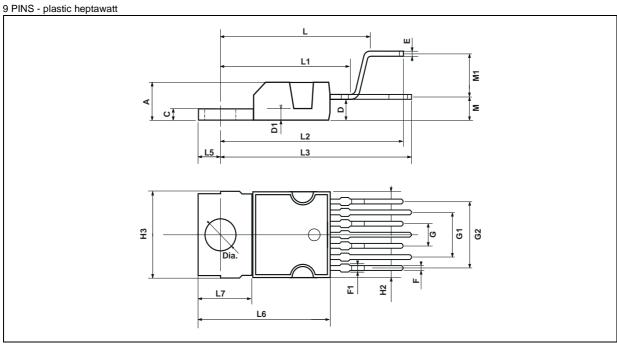
The power dissipated in the circuit is removed by adding an external heatsink. With the HEPTAWATT™ package, the heatsink is simply attached with a screw or a compression spring (clip).

A layer of silicon grease inserted between heatsink and package optimizes thermal contact; no electrical isolation is needed between the two surfaces since the tab is connected to Pin 4 which is ground.

Figure 6. Mounting examples



PACKAGE MECHANICAL DATA



Dimensions		Millimeters			Inches	
Dimensions	Min.	Тур.	Max.	Min.	Тур.	Max.
Α			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
Е	0.35		0.55	0.014		0.022
F	0.6		0.8	0.024		0.031
F1			0.9			0.035
G	2.41	2.54	2.67	0.095	0.100	0.105
G1	4.91	5.08	5.21	0.193	0.200	0.205
G2	7.49	7.62	7.8	0.295	0.300	0.307
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L		16.97			0.668	
L1		14.92			0.587	
L2		21.54			0.848	
L3		22.62			0.891	
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.260
М		2.8			0.110	
M1		5.08			0.200	
Dia.	3.65		3.85	0.144		0.152

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